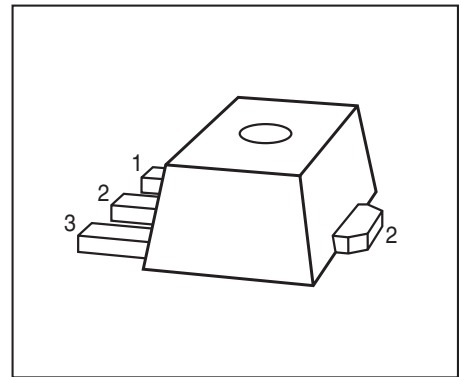


NPN Silicon Darlington Transistors

- For general AF applications
- High collector current
- High current gain
- Complementary types: BCV28, BCV48 (PNP)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



Type	Marking	Pin Configuration			Package
BCV29	EF	1=B	2=C	3=E	SOT89
BCV49	EG	1=B	2=C	3=E	SOT89

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}		V
BCV29		30	
BCV49		60	
Collector-base voltage	V_{CBO}		
BCV29		40	
BCV49		80	
Emitter-base voltage	V_{EBO}	10	
Collector current	I_C	500	mA
Peak collector current, $t_p \leq 10$ ms	I_{CM}	800	
Base current	I_B	100	
Peak base current	I_{BM}	200	
Total power dissipation- $T_S \leq 130$ °C	P_{tot}	1	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 20	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

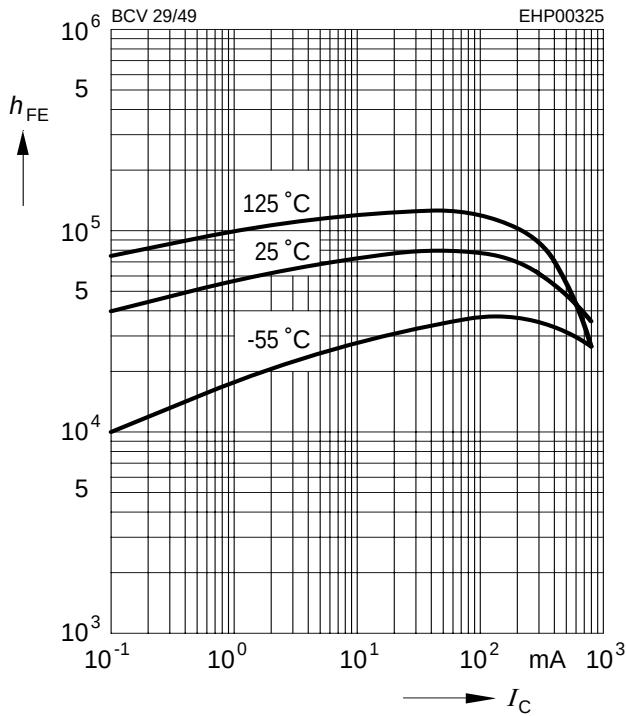
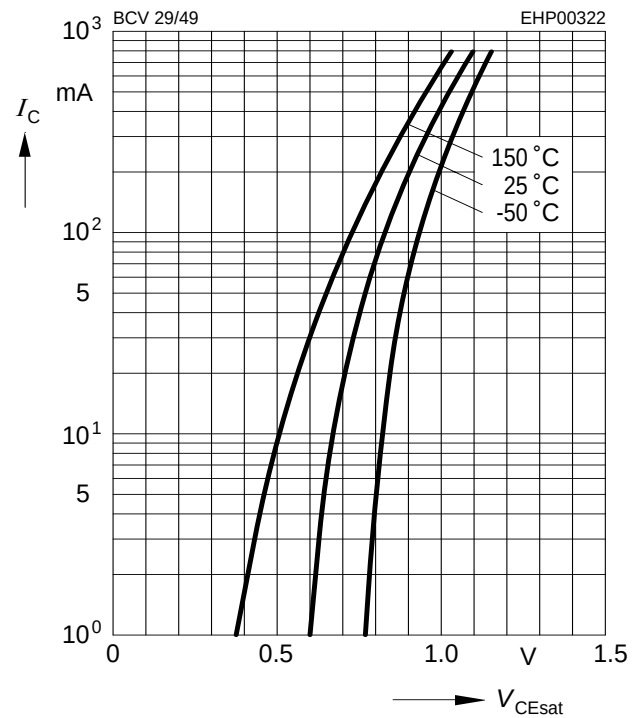
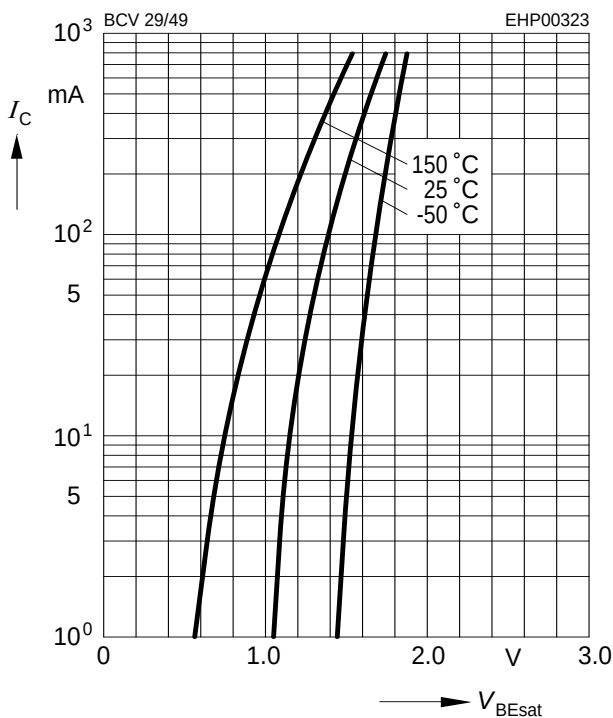
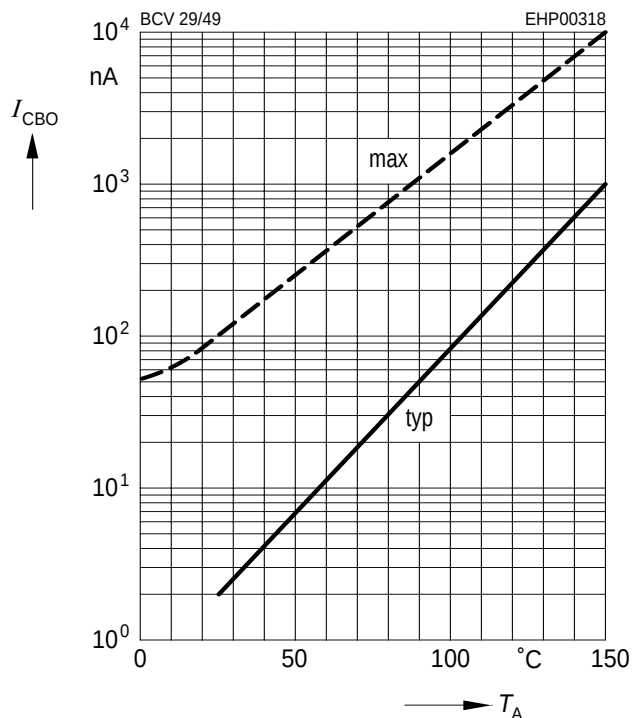
DC Characteristics

Collector-emitter breakdown voltage $I_C = 10\text{ mA}$, $I_B = 0$, BCV29 $I_C = 10\text{ mA}$, $I_B = 0$, BCV49	$V_{(BR)CEO}$	30 60	- -	- -	V
Collector-base breakdown voltage $I_C = 100\text{ }\mu\text{A}$, $I_E = 0$, BCV29 $I_C = 100\text{ }\mu\text{A}$, $I_E = 0$, BCV49	$V_{(BR)CBO}$	40 80	- -	- -	
Emitter-base breakdown voltage $I_E = 10\text{ }\mu\text{A}$, $I_C = 0$	$V_{(BR)EBO}$	10	-	-	
Collector-base cutoff current $V_{CB} = 30\text{ V}$, $I_E = 0$, BCV29 $V_{CB} = 60\text{ V}$, $I_E = 0$, BCV49 $V_{CB} = 30\text{ V}$, $I_E = 0$, $T_A = 150^\circ\text{C}$, BCV29 $V_{CB} = 60\text{ V}$, $I_E = 0$, $T_A = 150^\circ\text{C}$, BCV49	I_{CBO}	- - - -	- - - -	0.1 0.1 10 10	μA
Emitter-base cutoff current $V_{EB} = 4\text{ V}$, $I_C = 0$	I_{EBO}	-	-	100	nA
DC current gain ¹⁾ $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 1\text{ V}$, BCV29 $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 1\text{ V}$, BCV49 $I_C = 10\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 10\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV49 $I_C = 100\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 100\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV49 $I_C = 0.5\text{ A}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 0.5\text{ A}$, $V_{CE} = 5\text{ V}$, BCV49	h_{FE}	4000 2000 10000 4000 20000 10000 4000 2000	- - - - - - - -	- - - - - - - -	-
Collector-emitter saturation voltage ¹⁾ $I_C = 100\text{ mA}$, $I_B = 0.1\text{ mA}$	V_{CEsat}	-	-	1	V
Base emitter saturation voltage ¹⁾ $I_C = 100\text{ mA}$, $I_B = 0.1\text{ mA}$	V_{BEsat}	-	-	1.5	

¹Pulse test: $t < 300\mu\text{s}$; $D < 2\%$

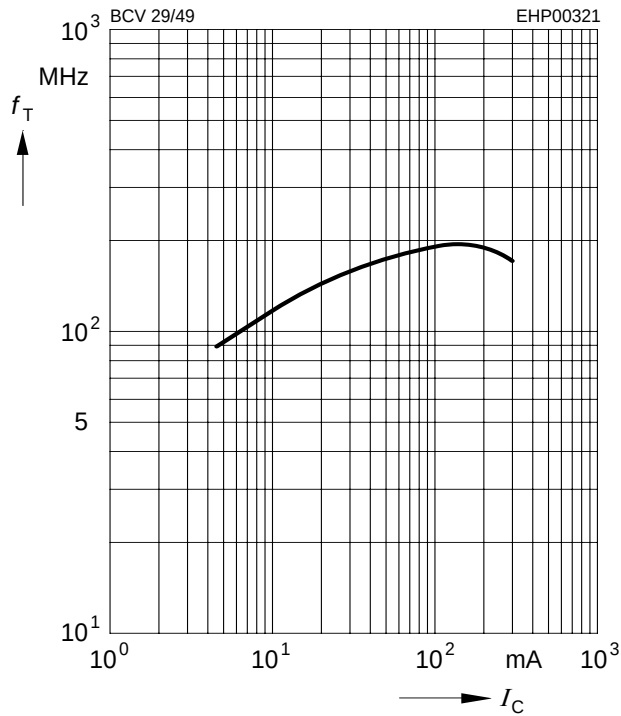
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Transition frequency $I_C = 50\text{ mA}$, $V_{CE} = 5\text{ V}$, $f = 100\text{ MHz}$	f_T	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10\text{ V}$, $f = 1\text{ MHz}$	C_{cb}	-	3	-	pF

DC current gain $h_{FE} = f(I_C)$
 $V_{CE} = 5 \text{ V}$

Collector-emitter saturation voltage
 $I_C = f(V_{CEsat}), h_{FE} = 1000$

Base-emitter saturation voltage
 $I_C = f(V_{BEsat}), h_{FE} = 1000$

Collector cutoff current $I_{CBO} = f(T_A)$
 $V_{CB} = V_{CEmax}$


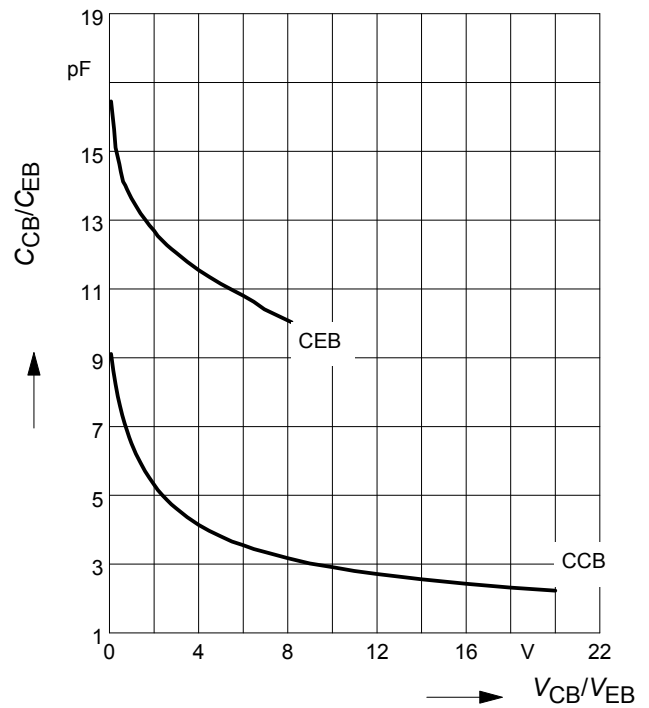
Transition frequency $f_T = f(I_C)$

$V_{CE} = 5\text{ V}$

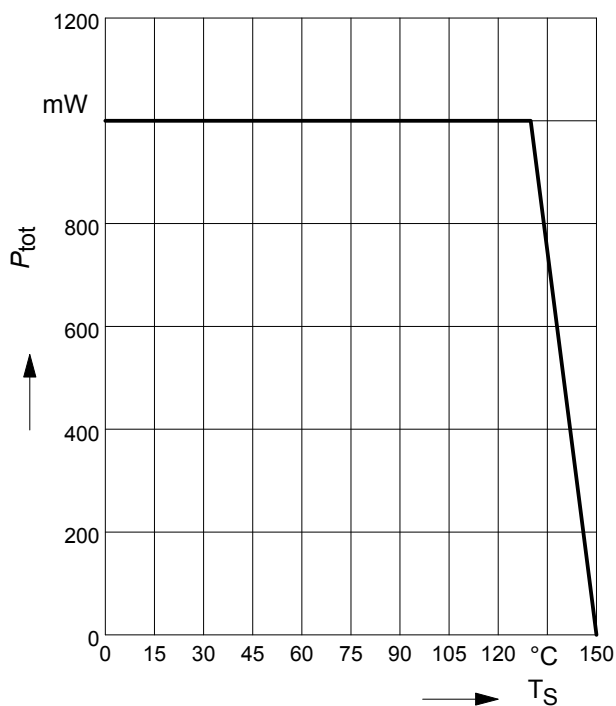


Collector-base capacitance $C_{cb} = f(V_{CB})$

Emitter-base capacitance $C_{eb} = f(V_{EB})$

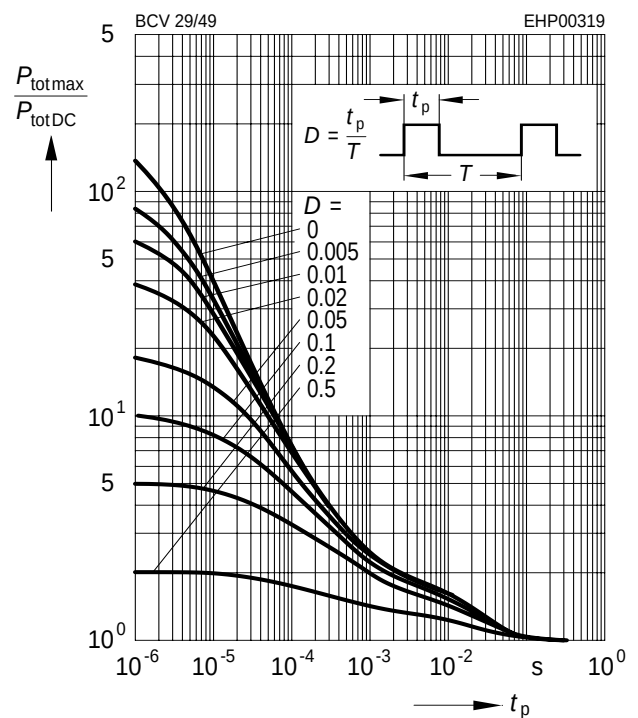


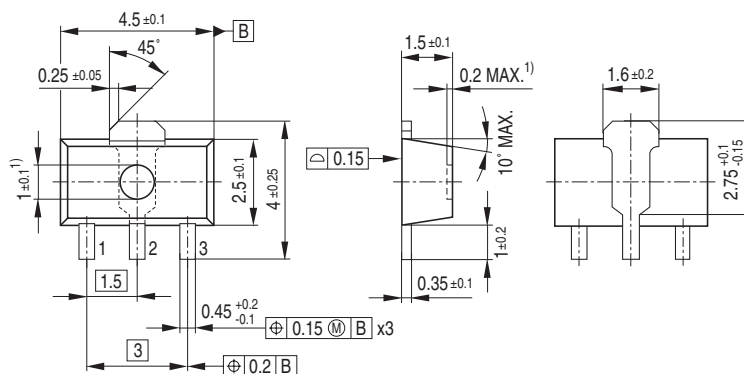
Total power dissipation $P_{tot} = f(T_S)$



Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$





Technical drawing of a mechanical part with the following dimensions:

- Overall width: 2.0
- Overall height: 2.5
- Bottom flange width: 0.8
- Bottom flange thickness: 0.7
- Central vertical slot width: 0.8
- Top flange width: 1.2
- Top flange thickness: 1.0

BAW78D
Type code

Pin 1

2005, June
Date code (YM)

Infineon
Manufacturer

Technical drawing of a 16-pin D-subminiature connector. The drawing includes a top view showing the pin layout with dimensions: 8mm between pin centers, 12mm total height, 4.6mm pin offset, and 4.3mm pin width. A side view shows a 0.2mm pin thickness and 1.6mm body height. A detail view of a pin is labeled "Pin 1".

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